IXYS

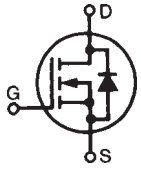
Advance Technical Information

TrenchT2™ Power MOSFET

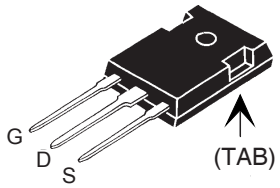
IXTH420N04T2

V_{DSS} = 40V
I_{D25} = 420A
$R_{DS(on)}$ ≤ 2.0mΩ

N-Channel Enhancement Mode
Avalanche Rated
Fast Intrinsic Diode



TO-247



G = Gate D = Drain
S = Source TAB = Drain

Symbol	Test Conditions	Maximum Ratings	
V_{DSS}	T_J = 25°C to 175°C	40	V
V_{DGR}	T_J = 25°C to 175°C, R_{GS} = 1MΩ	40	V
V_{GSM}	Transient	± 20	V
I_{D25}	T_C = 25°C (Chip Capability)	420	A
I_{LRMS}	Lead Current Limit, RMS	160	A
I_{DM}	T_C = 25°C, Pulse Width Limited by T_{JM}	1050	A
I_A	T_C = 25°C	200	A
E_{AS}	T_C = 25°C	960	mJ
P_D	T_C = 25°C	935	W
T_J		-55 ... +175	°C
T_{JM}		175	°C
T_{stg}		-55 ... +175	°C
T_L	1.6mm (0.062in.) from Case for 10s	300	°C
T_{sold}	Plastic Body for 10 seconds	260	°C
M_d	Mounting Torque	1.13 / 10	Nm/lb.in.
Weight		6	g

Symbol	Test Conditions (T_J = 25°C Unless Otherwise Specified)	Characteristic Values Min.	Typ.	Max.	
BV_{DSS}	V_{GS} = 0V, I_D = 250μA	40			V
$V_{GS(th)}$	$V_{DS} = V_{GS}$, I_D = 250μA	1.5		3.5	V
I_{GSS}	V_{GS} = ± 20V, V_{DS} = 0V			±200	nA
I_{DSS}	$V_{DS} = V_{DSS}$, V_{GS} = 0V			10	μA
	T_J = 150°C			300	μA
$R_{DS(on)}$	V_{GS} = 10V, I_D = 100A, Note 1		1.6	2.0	mΩ

Features

- International Standard Package
- 175°C Operating Temperature
- High Current Handling Capability
- Avalanche Rated
- Fast Intrinsic Diode
- Low $R_{DS(on)}$

Advantages

- Easy to Mount
- Space Savings
- High Power Density

Applications

- DC/DC Converters and Off-line UPS
- Primary- Side Switch
- High Current Switching Applications

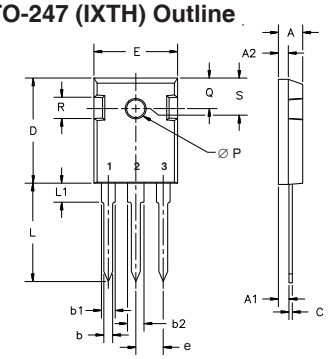
Symbol	Test Conditions (T_J = 25°C, Unless Otherwise Specified)	Characteristic Values Min.	Typ.	Max.	
g_{fs}	V_{DS} = 10V, I_D = 60A, Note 1	70	120		S
C_{iss}	V_{GS} = 0V, V_{DS} = 25V, f = 1MHz		19.7		nF
C_{oss}			3220		pF
C_{rss}			690		pF
R_{Gi}	Gate Input Resistance		1.45		Ω
$t_{d(on)}$	**Resistive Switching Times**		23		ns
t_r	V_{GS} = 10V, V_{DS} = 0.5 • V_{DSS}, I_D = 100A		27		ns
$t_{d(off)}$	R_G = 2Ω (External)		70		ns
t_f			155		ns
$Q_{g(on)}$	V_{GS} = 10V, V_{DS} = 0.5 • V_{DSS}, I_D = 0.5 • I_{D25}		315		nC
Q_{gs}			68		nC
Q_{gd}			73		nC
R_{thJC}				0.16	°C/W
R_{thCH}			0.21		°C/W

Source-Drain Diode

Symbol	Test Conditions (T_J = 25°C, Unless Otherwise Specified)	Characteristic Values Min.	Typ.	Max.	
I_S	V_{GS} = 0V			420	A
I_{SM}	Repetitive, Pulse Width Limited by T_{JM}			1680	A
V_{SD}	I_F = 100A, V_{GS} = 0V, Note 1			1.3	V
t_{rr}	I_F = 150A, V_{GS} = 0V		74		ns
I_{RM}	-di/dt = 100A/μs		2.7		A
Q_{RM}	V_R = 20V		100		nC

Note 1. Pulse test, t ≤ 300μs; duty cycle, d ≤ 2%.

TO-247 (IXTH) Outline



Terminals: 1 - Gate 2 - Drain
3 - Source Tab - Drain

Dim.	Millimeter Min.	Max.	Inches Min.	Max.
A	4.7	5.3	.185	.209
A_1	2.2	2.54	.087	.102
A_2	2.2	2.6	.059	.098
b	1.0	1.4	.040	.055
b_1	1.65	2.13	.065	.084
b_2	2.87	3.12	.113	.123
C	.4	.8	.016	.031
D	20.80	21.46	.819	.845
E	15.75	16.26	.610	.640
e	5.20	5.72	0.205	0.225
L	19.81	20.32	.780	.800
L1		4.50		.177
ØP	3.55	3.65	.140	.144
Q	5.89	6.40	0.232	0.252
R	4.32	5.49	.170	.216
S	6.15 BSC		242 BSC	

ADVANCE TECHNICAL INFORMATION

The product presented herein is under development. The Technical Specifications offered are derived from a subjective evaluation of the design, based upon prior knowledge and experience, and constitute a "considered reflection" of the anticipated result. IXYS reserves the right to change limits, test conditions, and dimensions without notice.

Fig. 1. Output Characteristics @ 25ºC

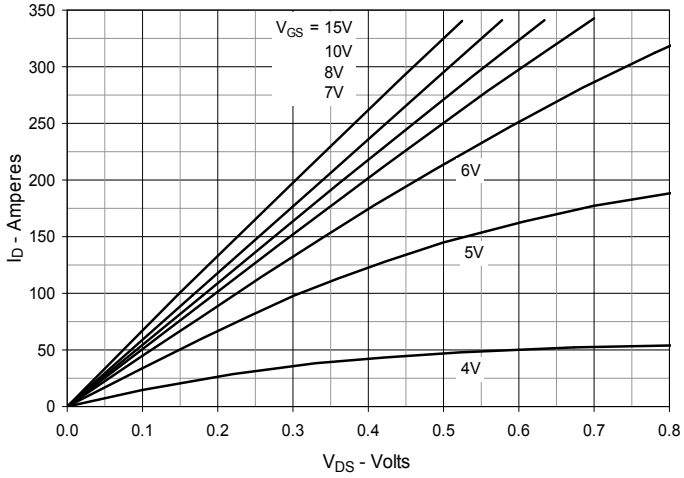


Fig. 2. Extended Output Characteristics @ 25ºC

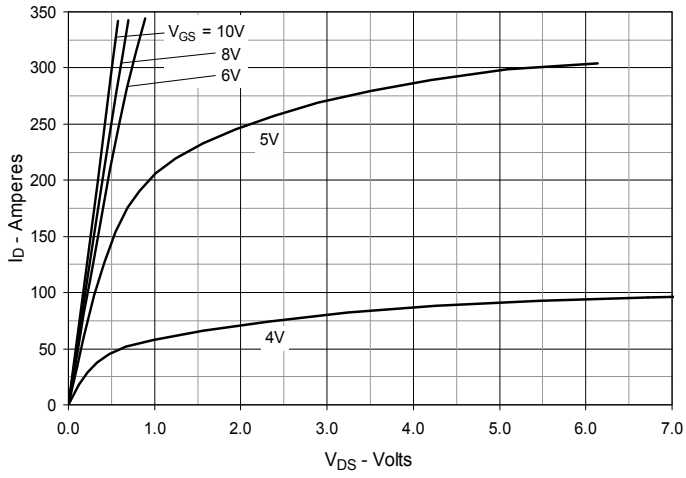


Fig. 3. Output Characteristics @ 150ºC

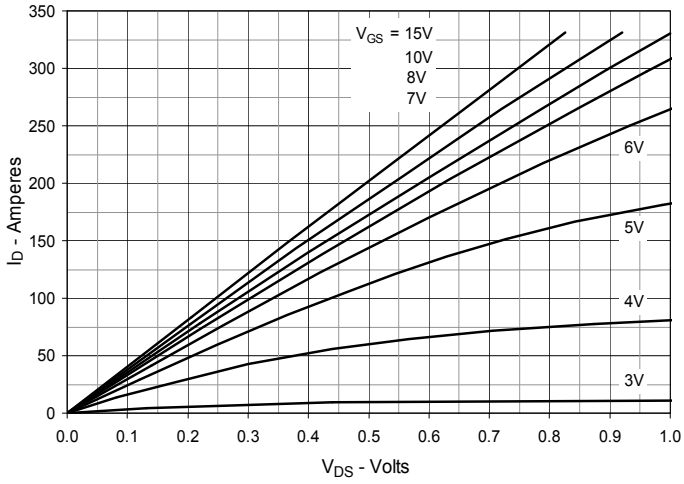


Fig. 4. $R_{DS(on)}$ Normalized to I_D = 210A Value vs. Junction Temperature

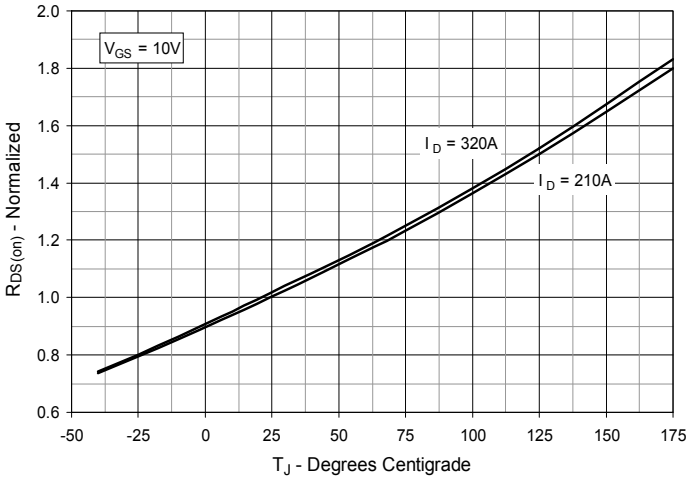


Fig. 5. $R_{DS(on)}$ Normalized to I_D = 210A Value vs. Drain Current

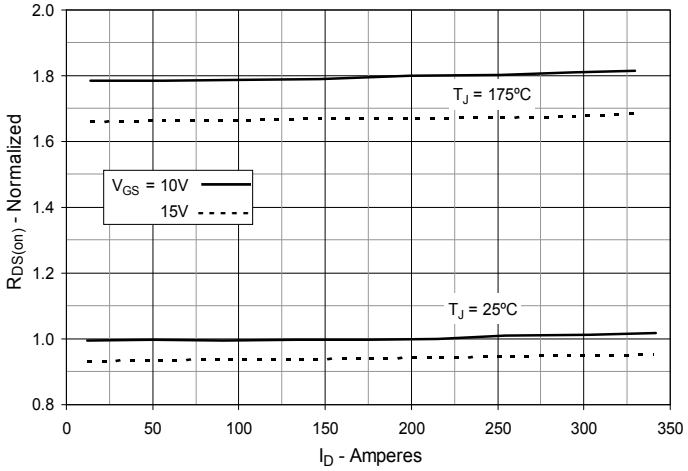


Fig. 6. Drain Current vs. Case Temperature

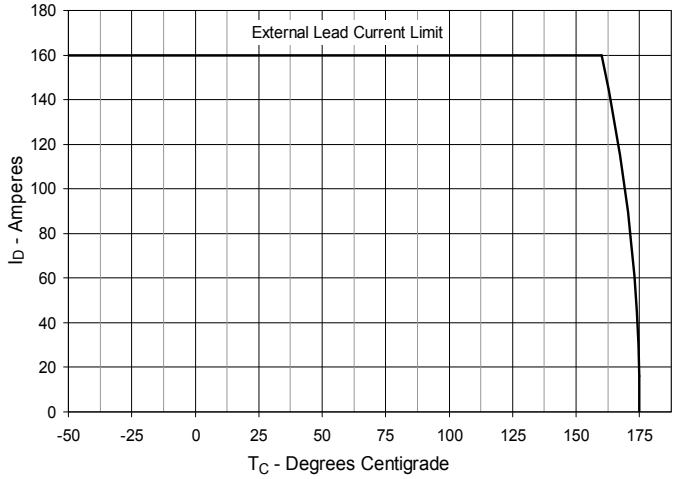


Fig. 7. Input Admittance

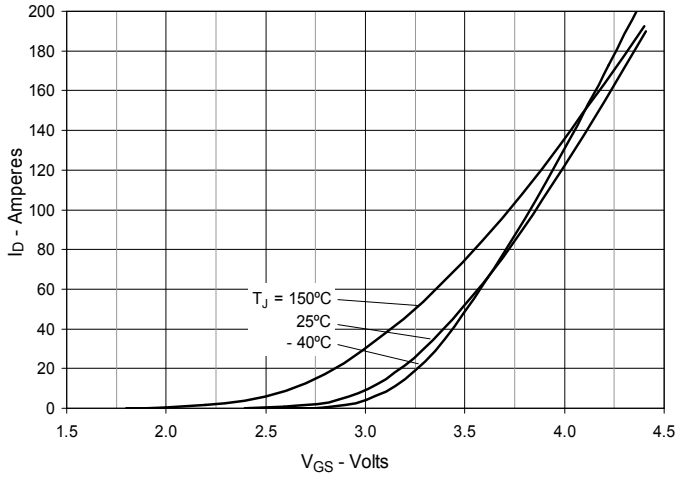


Fig. 8. Transconductance

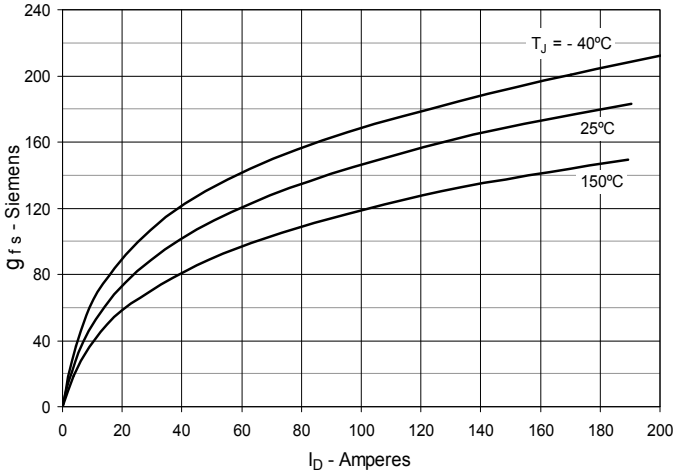


Fig. 9. Forward Voltage Drop of Intrinsic Diode

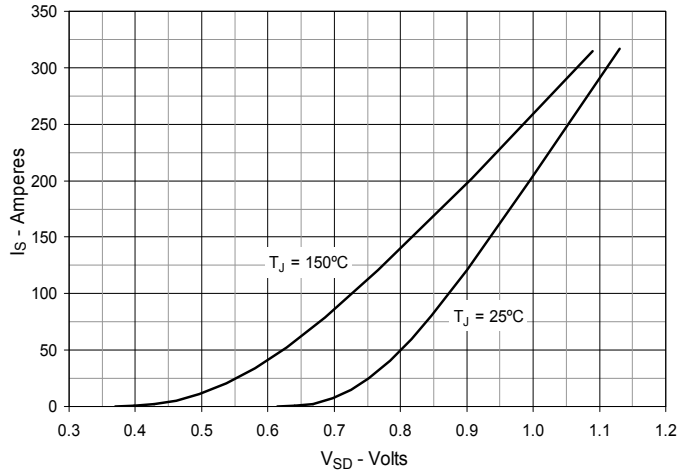


Fig. 10. Gate Charge

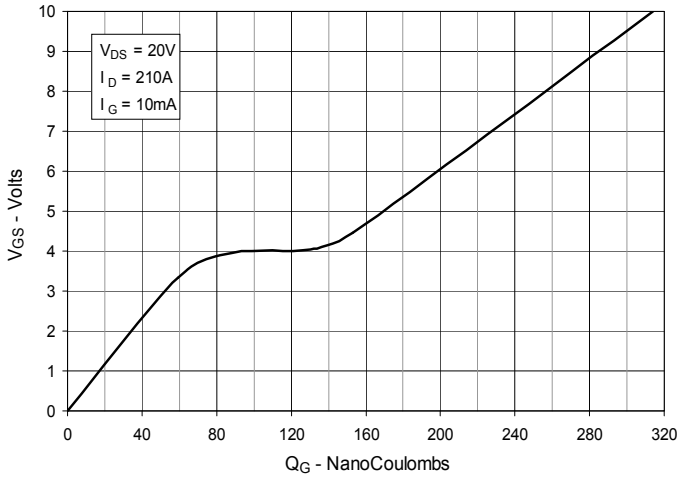


Fig. 11. Capacitance

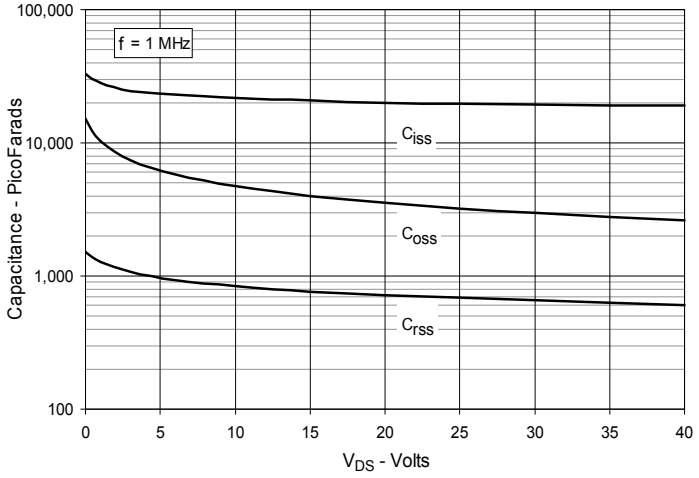


Fig. 12. Forward-Bias Safe Operating Area

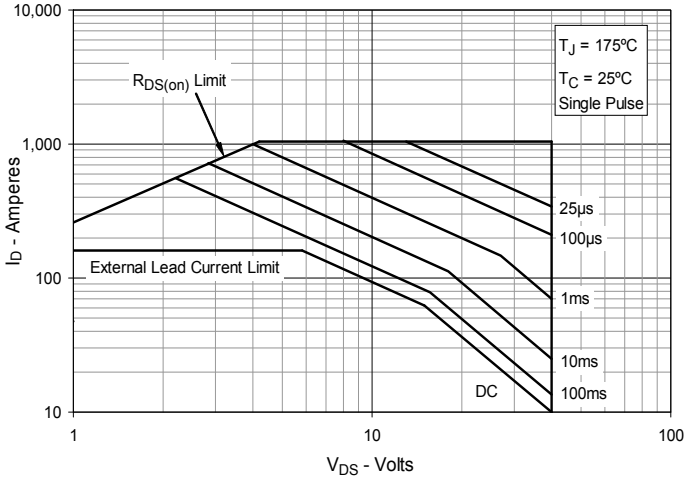


Fig. 13. Resistive Turn-on Rise Time vs. Junction Temperature

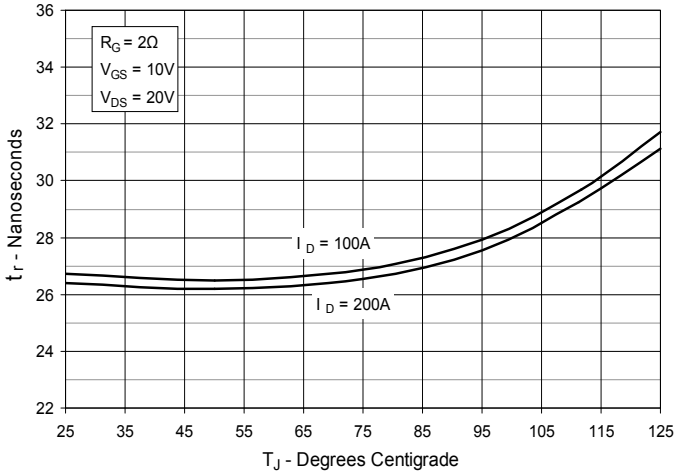


Fig. 14. Resistive Turn-on Rise Time vs. Drain Current

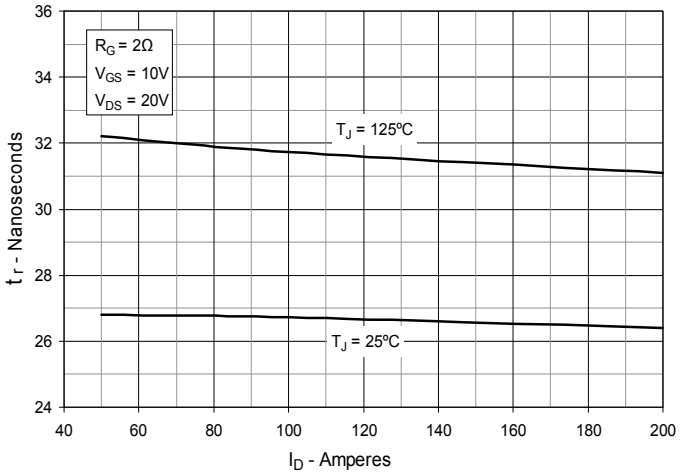


Fig. 15. Resistive Turn-on Switching Times vs. Gate Resistance

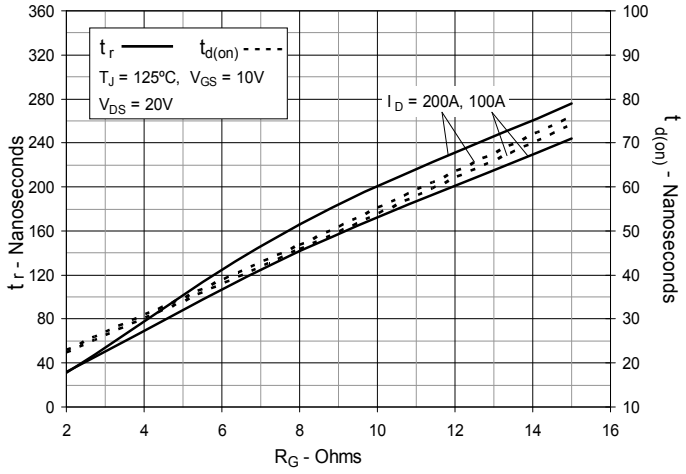


Fig. 16. Resistive Turn-off Switching Times vs. Junction Temperature

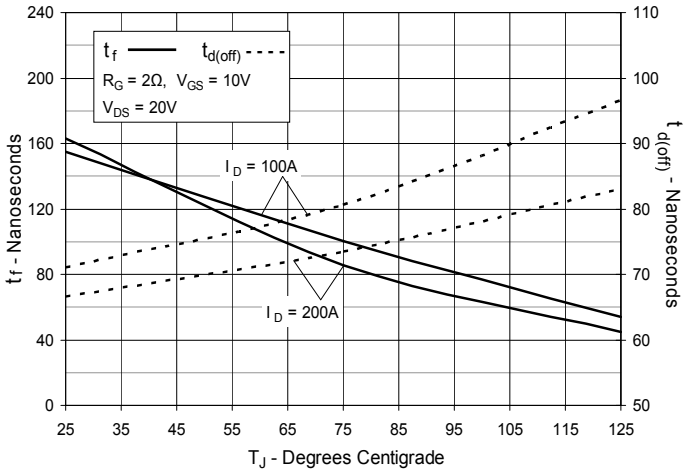


Fig. 17. Resistive Turn-off Switching Times vs. Drain Current

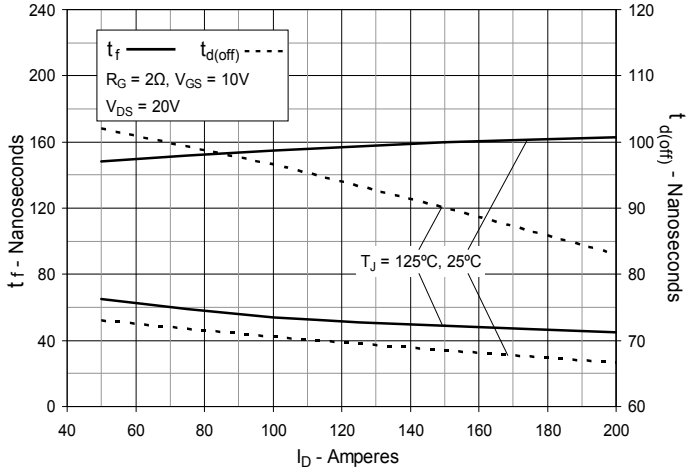


Fig. 18. Resistive Turn-off Switching Times vs. Gate Resistance

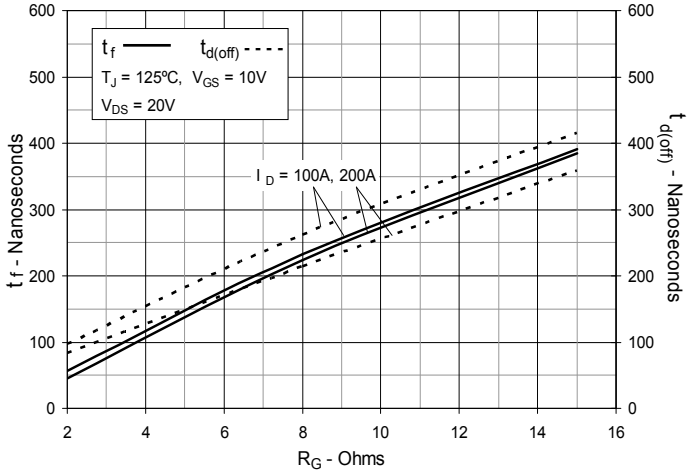


Fig. 19. Maximum Transient Thermal Impedance